

IN THE ABSTRACT

Please replace the Abstract at page 37 with the following new Abstract.

A stackable semiconductor package includes a substrate having a first surface, an opposite second surface, and through hole. Circuit patterns on the first and second surfaces of the substrate include lands, and the circuit patterns of the second surface also include bond fingers. A semiconductor chip is in the throughhole. The semiconductor chip has bond pads, which are oriented in a same direction as the second surface of the substrate. Wires electrically connect the bond pads to the bond fingers. An encapsulant fills the through hole and covers the semiconductor chip, the wires and the bond fingers, without covering the lands. Conductive balls are fused to the lands of the first surface of the substrate. A second semiconductor package may be stacked on the second surface of the substrate, and conductive balls of the second semiconductor package may be fused to the lands of the second surface.